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(Original Signature of Member)

119TH CONGRESS
2D SESSION

H. R. _____

To provide for export restrictions on certain semiconductor manufacturing equipment and components therefor, and for other purposes.

IN THE HOUSE OF REPRESENTATIVES

M. _____ introduced the following bill; which was referred to the
Committee on _____

A BILL

To provide for export restrictions on certain semiconductor manufacturing equipment and components therefor, and for other purposes.

1 *Be it enacted by the Senate and House of Representa-*
2 *tives of the United States of America in Congress assembled,*

3 **SECTION 1. SHORT TITLE.**

4 This Act may be cited as the “Multilateral Alignment
5 of Technology Controls on Hardware Act” or the
6 “MATCH Act”.

7 **SEC. 2. SENSE OF CONGRESS.**

8 It is the sense of Congress that—

1 (1) export controls on semiconductor manufac-
2 turing equipment and components represent one of
3 the United States' most effective defenses of this
4 foundational technology;

5 (2) advanced computing applications like artifi-
6 cial intelligence are transforming military affairs and
7 the balance of power;

8 (3) the United States and its allies have an ad-
9 vantage in the foundational technologies that under-
10 pin advanced computing applications, including ad-
11 vanced-node integrated circuits and production, and
12 the equipment and software required to design and
13 produce advanced-node integrated circuits;

14 (4) robust controls on semiconductor manufac-
15 turing equipment and components have been a bi-
16 partisan priority across multiple administrations, re-
17 flecting a shared recognition that protecting Amer-
18 ica's semiconductor advantage is essential to na-
19 tional security;

20 (5) the adversaries of the United States are ex-
21 ploiting gaps in the current export control regime;

22 (6) certain entities, including ChangXin Mem-
23 ory Technologies (CXMT), Hua Hong, Semicon-
24 ductor Ltd. (Hua Hong), Huawei, Technologies Co.
25 Ltd. (Huawei), Semiconductor Manufacturing Inter-

1 national Corporation (SMIC), Yangtze Memory
2 Technologies Corp. (YMTC), Advanced Micro-Fab-
3 rication Equipment Inc. China (AMEC), Beijing E-
4 Town Semiconductor Technology Co., Ltd. (E-Town
5 Semiconductor), NAURA Technology Group Co.,
6 Ltd. (NAURA), Piotech Semiconductor Equipment
7 Co., Ltd. (Piotech), ACM Research, Inc. (ACM Re-
8 search), PNC Process Systems Co., Ltd. (PNC
9 Process Systems), Skyverse Technology Co.
10 (Skyverse), Shanghai Micro Electronics Equipment
11 (Group) (SMEE), Kingsemi Co., Ltd. (Kingsemi),
12 and Hwatsing Technology Co. Ltd. (Hwatsing) are
13 engaged in efforts to produce advanced-node inte-
14 grated circuits and especially crucial for the Mili-
15 tary-Civil Fusion efforts of the People's Republic of
16 China and warrant comprehensive export controls to
17 prevent those companies from accessing items made
18 with United States technologies;

19 (7) companies located in adversary countries
20 that produce semiconductor manufacturing equip-
21 ment are critical to adversaries' efforts to develop
22 advanced-node integrated circuit production capabili-
23 ties and overcome export controls, and should not be
24 permitted to utilize or benefit from United States' or
25 allied technology or components; and

1 (8) the United States Government should work
2 closely with allies and partners of the United States
3 to align export controls on semiconductor manufac-
4 turing equipment and components to prevent gaps in
5 controls, reduce the risk of circumvention, and en-
6 sure a level global playing field.

7 **SEC. 3. REPORT AND APPLICATION OF CONTROLS.**

8 (a) IDENTIFYING CHOKEPOINTS.—Not later than 60
9 days after the date of the enactment of this Act, and annu-
10 ally thereafter, the covered agency heads shall—

11 (1) jointly conduct a review to identify all cov-
12 ered semiconductor manufacturing equipment and
13 all covered facilities; and

14 (2) submit to the appropriate congressional
15 committees a list of all such equipment and covered
16 facilities.

17 (b) DIPLOMATIC ENGAGEMENT.—

18 (1) IN GENERAL.—The covered agency heads
19 shall prioritize and upon enactment of this Act im-
20 mediately engage diplomatically to seek for the gov-
21 ernments of allied supplier countries to adopt—

22 (A) countrywide controls on covered semi-
23 conductor manufacturing equipment subject to
24 the allied supplier country's jurisdiction, or

1 other controls and licensing policies having the
2 same practical effect; and

3 (B) license requirements for the export of
4 all applicable items to any covered facility, and
5 the servicing of all applicable items at any cov-
6 ered facilities, with a licensing policy of denial.

7 (2) BRIEFING ON DIPLOMATIC EFFORTS.—Not
8 later than 90 days after the date of the enactment
9 of this Act, the covered agency heads shall provide
10 a briefing to members of the appropriate congress-
11 sional committees that—

12 (A) describes the status of diplomatic ef-
13 forts to secure the adoption by allied supplier
14 countries of the controls described in paragraph
15 (1);

16 (B) outlines and assesses incentives to en-
17 courage adoption of these controls; and

18 (C) identifies—

19 (i) allied supplier countries that have
20 not adopted the controls described in para-
21 graph (1)(A);

22 (ii) allied supplier countries that have
23 not adopted the controls described in para-
24 graph (1)(B); and

1 (iii) measures that the United States
2 has taken or plans to take to implement
3 the controls described in paragraph (1).

4 (c) EXHAUSTION OF DIPLOMATIC RECOURSE AND
5 APPLICATION OF CONTROLS.—

6 (1) APPLICATION OF CONTROLS.—Not later
7 than 150 days after the enactment of this Act, and
8 annually thereafter, the covered agency heads shall
9 publish regulations that—

10 (A) ensure all U.S. countrywide controls
11 include all U.S.-origin covered semiconductor
12 manufacturing equipment; and

13 (B) ensure all covered facilities in coun-
14 tries of concern are subject to comprehensive
15 U.S. restrictions.

16 (2) EXHAUSTION OF DIPLOMATIC RECOURSE.—
17 By the date that is 150 days after the date of the
18 enactment of this Act, the covered agency heads
19 shall jointly either—

20 (A) certify to the appropriate congressional
21 committees that all allied supplier countries
22 have implemented—

23 (i) countrywide controls over all cov-
24 ered semiconductor manufacturing equip-
25 ment subject to the allied supplier coun-

1 try’s jurisdiction, or other controls and li-
2 censing policies having the same practical
3 effect; and

4 (ii) license requirements for all appli-
5 cable items, with a licensing policy of de-
6 nial, or other controls and licensing policies
7 having the same practical effect; or

8 (B) provide a list to the appropriate con-
9 gressional committees of any allied supplier
10 countries that have not implemented all controls
11 described in subparagraph (A)(i) or (ii).

12 (3) EXTENSION OF CONTROLS.—Unless the
13 covered agency heads provide the certification in
14 subparagraph (A), the covered agency heads shall
15 issue regulations that—

16 (A) establish U.S. jurisdiction over and
17 apply countrywide controls to all covered semi-
18 conductor manufacturing equipment and com-
19 ponents therefor exported from countries identi-
20 fied by the covered agency heads under sub-
21 section (c)(2)(B), whether by establishing juris-
22 diction over such items and applying controls
23 directly, or by restricting the end-uses of essen-
24 tial components of such equipment that are al-
25 ready subject to U.S. jurisdiction, or both;

1 (B) require a license for all servicing of
2 any applicable item located in any covered facil-
3 ity, and implement a policy of denial for such
4 servicing; and

5 (C) establish jurisdiction over, and apply
6 end-user or end-use controls prohibiting, the ex-
7 port from countries identified by the covered
8 agency heads under subsection (c)(2)(B) of all
9 applicable items to any covered facility.

10 (d) NATIONAL SECURITY WAIVER.—The covered
11 agency heads may jointly grant a one-time waiver to ex-
12 tend the 150-day deadline under subsection (c) by not
13 more than 90 days, if the covered agency heads, with con-
14 currence from the Secretary of Defense and the Secretary
15 of Energy, jointly—

16 (1) determine and certify to the appropriate
17 congressional committees that—

18 (A) the extension is in the national secu-
19 rity interest of the United States, despite the
20 risk that countries of concern may take advan-
21 tage of the delay to further stockpile covered
22 semiconductor manufacturing equipment; and

23 (B) the governments of an allied supplier
24 country or countries are taking concrete,
25 verifiable steps, pursuant to their domestic laws

1 and regulations and as expeditiously as possible,
2 to adopt and implement controls that are
3 fully-aligned with, or more stringent than, the
4 controls that would otherwise be imposed under
5 subsection (c)(3); and

6 (2) submit a report to the appropriate congressional
7 committees describing—

8 (A) the details justifying the national security
9 interest determination and progress that is
10 intended to be achieved by the extension; and

11 (B) the concrete and verifiable interim
12 steps the covered agency heads have taken to
13 prevent stockpiling of covered semiconductor
14 manufacturing equipment by countries of concern.
15

16 (e) REPORT.—Not later than 180 days after the date
17 of the enactment of this Act, and annually thereafter, the
18 covered agency heads shall provide to the appropriate congressional
19 committees a report that includes—

20 (1) a list of all covered semiconductor manufacturing
21 equipment;

22 (2) a list of all covered facilities and all entities
23 that own or operate any covered facility;

24 (3) the scope of the controls described in subsection
25 (b)(1) imposed by the United States and al-

1 lied supplier countries for all covered semiconductor
2 manufacturing equipment identified pursuant to
3 paragraph (1);

4 (4) a summary of diplomatic engagements and
5 unilateral actions undertaken in the 12-months pe-
6 riod prior to the submission of the report to close
7 any gap in the controls described in subsection
8 (b)(1) among allied supplier countries; and

9 (5) a certification that the export of all covered
10 semiconductor manufacturing equipment to a coun-
11 try of concern, and the export, reexport, or transfer,
12 or servicing of all applicable items to any covered fa-
13 cility, requires a United States or allied license and
14 applications for such licenses will be reviewed under
15 a policy of denial.

16 (f) TERMINATION AND REIMPOSITION OF CONTROLS
17 UPON ALLIED ACTION.—

18 (1) TERMINATION OR MODIFICATION.—If the
19 covered agency heads determine that an allied sup-
20 plier country has implemented all the controls in
21 (c)(2)(A)(i) and (ii), the covered agency heads may,
22 upon notifying the appropriate congressional com-
23 mittees of such determination, terminate or modify
24 any control imposed under subsection (c)(3) for
25 items exported from that allied supplier country.

1 (2) REIMPOSITION.—If, after terminating or
2 modifying a control under paragraph (1), the cov-
3 ered agency heads determine that the allied supplier
4 country has materially weakened, suspended, or re-
5 voked the control or licensing policy of denial that
6 justified the termination or modification under para-
7 graph (1), the covered agency heads shall, not later
8 than 60 days after making such determination—

9 (A) notify the appropriate congressional
10 committees of such determination; and

11 (B) reimpose the control under subsection
12 (c)(2) that was terminated or modified under
13 paragraph (1).

14 (g) ADMINISTRATIVE PROCEDURE ACT RULEMAKING
15 AND JUDICIAL REVIEW.—The provisions of section 1762
16 of the Export Control Reform Act of 2018 (50 U.S.C.
17 4821) shall apply to this Act in the same manner and to
18 the same extent as such provisions apply to the Export
19 Control Reform Act of 2018.

20 (h) SUNSET.—

21 (1) EXPIRATION.—This Act shall cease to have
22 effect on the date that is 5 years after the date of
23 the enactment of this Act.

24 (2) CONTINUATION OF PRIOR OBLIGATIONS.—
25 The expiration of this Act under subsection (a) shall

1 not affect any action, proceeding, or obligation that
2 was commenced or incurred prior to such expiration.

3 (i) DEFINITIONS.—In this section:

4 (1) ADVANCED-NODE INTEGRATED CIRCUITS.—

5 The term “advanced-node integrated circuits” has
6 the meaning given that term in section 772.1 of the
7 Export Administration Regulations.

8 (2) ALLIED SUPPLIER COUNTRY.—The term
9 “allied supplier country” means any country that—

10 (A) is not a country of concern; and

11 (B) is engaged in the production of covered
12 semiconductor manufacturing equipment.

13 (3) APPLICABLE ITEM.—The term “applicable
14 item” means any item that is or can be made sub-
15 ject to the Export Administration Regulations, in-
16 cluding—

17 (A) a foreign-produced item that is the di-
18 rect product of, or produced by plants or major
19 components that are themselves the direct prod-
20 uct of software or technology subject to the Ex-
21 port Administration Regulations;

22 (B) a foreign-produced item with more
23 than zero percent de minimis controlled United
24 States-origin content; and

1 (C) a foreign-produced item that contain
2 United States-origin or foreign-produced inte-
3 grated circuits that are presumptively designed
4 or produced, directly or indirectly, with tech-
5 nology, software, or equipment that is subject
6 to the Export Administration Regulations.

7 (4) APPROPRIATE CONGRESSIONAL COMMIT-
8 TEES.—The term “appropriate congressional com-
9 mittees” means—

10 (A) the Committee on Banking, Housing,
11 and Urban Affairs of the Senate; and

12 (B) the Committee on Foreign Affairs of
13 the House of Representatives.

14 (5) COUNTRY OF CONCERN.—The term “coun-
15 try of concern” means—

16 (A) the People’s Republic of China, includ-
17 ing the Hong Kong and Macau Special Admin-
18 istrative Regions;

19 (B) the Republic of Cuba;

20 (C) the Islamic Republic of Iran;

21 (D) the Democratic People’s Republic of
22 Korea;

23 (E) the Russian Federation; and

24 (F) any other foreign country listed in the
25 Country Group D:5 under Supplement No. 1 to

1 part 740 of the Export Administration Regula-
2 tions, as published on January 1, 2026, that is
3 designated by the Secretary of State as a coun-
4 try of concern for purposes of this section and
5 for which notice of such designation has been
6 published in the Federal Register.

7 (6) COUNTRYWIDE CONTROLS.—The term
8 “countrywide controls” means licensing require-
9 ments and a policy of denial for the export, reexport,
10 transfer or servicing of all specified items to any
11 destination within any country of concern, excluding
12 exports where the destination is a fabrication facility
13 that existed as of the date of the enactment of this
14 Act and remains owned and operated by a company
15 headquartered, and having an ultimate parent
16 headquartered, outside of any country of concern.

17 (7) COVERED AGENCY HEADS.—The term “cov-
18 ered agency heads” means the Under Secretary of
19 Commerce for Industry and Security and the Sec-
20 retary of State, in coordination with the Secretary of
21 Energy and the Secretary of Defense, or their des-
22 ignees.

23 (8) COVERED FACILITY.—The term “covered
24 facility” means any facility—

25 (A) which is—

- 1 (i) located in a country of concern;
- 2 (ii) engaged in the production of ad-
- 3 vanced-node integrated circuits; and
- 4 (iii) not a fabrication facility that—
- 5 (I) existed as of the date of the
- 6 enactment of this Act; and
- 7 (II) remains owned and operated
- 8 by a company which is headquartered
- 9 and has an ultimate parent
- 10 headquartered outside of any country
- 11 of concern; or
- 12 (B) which is or ever has been owned or
- 13 controlled by, under common ownership or con-
- 14 trol with, or manufacturing at the direction
- 15 of—
- 16 (i) any entity described in section
- 17 5949(j)(3)(A) or (B);
- 18 (ii) Huawei or Hua Hong;
- 19 (iii) any producer, manufacturer, or
- 20 developer of semiconductor manufacturing
- 21 equipment that is headquartered in, or has
- 22 an ultimate parent headquartered in, a
- 23 country of concern; or
- 24 (iv) any entity that is a subsidiary, af-
- 25 filiate, or successor to, or has a joint ven-

1 ture, teaming agreement, joint develop-
2 ment or research agreement, technology
3 transfer or collaboration agreement, or
4 other similar type of arrangement with an
5 entity described in paragraph (10)(B)(i),
6 (ii), or (iii).

7 (9) COVERED SEMICONDUCTOR MANUFAC-
8 TURING EQUIPMENT.—The term “covered semicon-
9 ductor manufacturing equipment”—

10 (A) means semiconductor manufacturing
11 equipment or a component therefor that—

12 (i) is an applicable item; and

13 (ii) the covered agency heads deter-
14 mine no country of concern produces in
15 high volume and with capabilities com-
16 parable to those of the product sold by the
17 global market leader, as of the date of the
18 enactment of this Act; and

19 (B) includes, at a minimum—

20 (i) all semiconductor manufacturing
21 equipment, materials, and software that at
22 the date of passage of this Act require a
23 license for export, re-export, or in-country
24 transfer to any destination in a country of
25 concern;

1 (ii) all deep ultraviolet immersion pho-
2 tolithography machines, through silicon via
3 deposition and etch tools, cryogenic etch
4 equipment, and cobalt deposition equip-
5 ment, regardless of overlay or other per-
6 formance characteristics; and

7 (iii) presumptively, all semiconductor
8 manufacturing equipment or components
9 specified in Export Control Classification
10 Number 3B001, 3B002, or 3B993 as of
11 the date of the enactment of this Act, ex-
12 cept any items the covered agency heads
13 determine are not covered semiconductor
14 manufacturing equipment.

15 (10) EXPORT; IN-COUNTRY TRANSFER; REEX-
16 PORT; EXPORT ADMINISTRATION REGULATION.—The
17 terms “export”, “in-country transfer”, “reexport”,
18 and “Export Administration Regulations” have the
19 meanings given such terms in section 1742 of the
20 Export Control Reform Act of 2018 (50 U.S.C.
21 4801).

22 (11) SERVICING.—The term “servicing” means
23 any servicing of equipment or components, whether
24 in-person or remote, including installation, calibra-
25 tion, repair, overhauling, refurbishing, testing, diag-

1 nosing, updating software or firmware, training,
2 field services, application support engineering,
3 customization, technical assistance, process adjust-
4 ments, troubleshooting, and transfer of industry best
5 practices for maintenance.